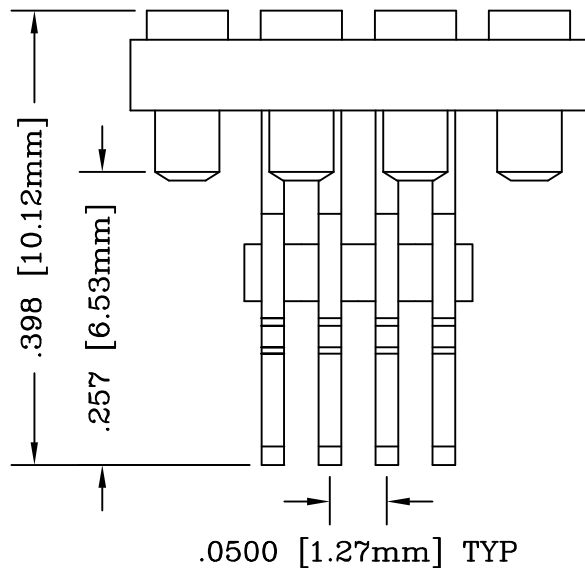
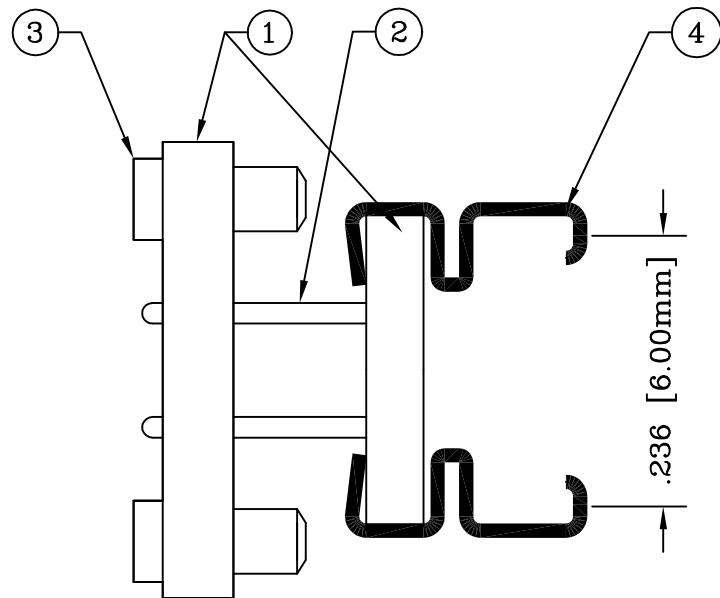
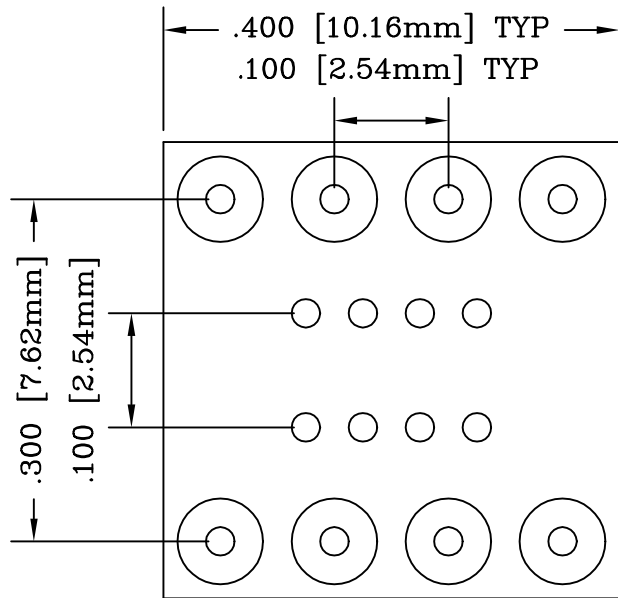


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	12/21/94	P.M.
B	UPDATED DWG & ADDED NOTES	02/27/03	H.N.

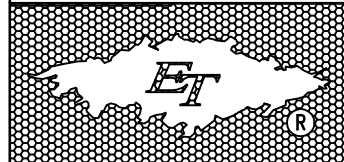
F2435
DOD 32435



NOTES:

1. SUBSTRATE: 0.0625"±0.007" FR4/G10 OR EQUIVALENT HIGH TEMP MATERIAL. 1/2 OZ. Cu CLAD. SnPb PLATING.
2. PINS: MATERIAL-BRASS ALLOY 360 1/2 HARD; FINISH-10μ" Au OVER 50μ" Ni (MIN.).
3. PINS: SHELL MATERIAL-BRASS ALLOY 360 1/2 HARD; FINISH-10μ" Au OVER 50μ" Ni (MIN.). CONTACT MATERIAL-BeCu; FINISH 10μ" Au OVER 100μ" Ni (MIN.).
4. LEADS: MATERIAL-BeCu ALLOY 194; PLATING-80/20 SnPb.

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.

— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051
TEL:(408)982-0660 FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 02/27/03	REVISION: B	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: ASDIP.3008S0011	DESCRIPTION: AS-DIP.3-008-S001-1
Scale 6:1	DO NOT SCALE DRAWING		